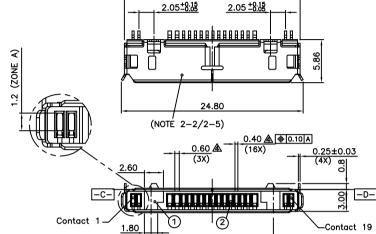
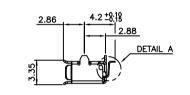
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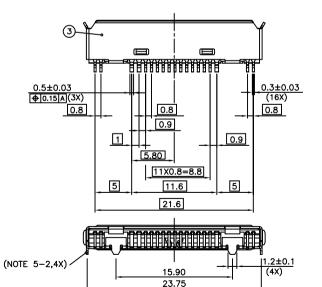
 PRODUCT NUMBER
 REMARK

 54040-001
 BOTTOM MOUNT

 54040-001-LF
 BOTTOM MOUNT

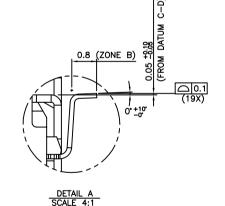






1 2

16.70



(NOTE 2-2/2-5) 4X

NOTES:

MATERIAL
 1-1 ① HOUSING: HIGH TEMP. PLASTIC, LCP OR EQUIVALENT.

UL94V-0, COLOR BLACK.

1-2 ② CONTACT: COPPER ALLOY. THICKNESS: 0.15±0.02 mm.
RAW MAT'L MUST SUPPLIED BY NIPPON MINING.

1-3 (3) SHIELD: STAINLESS STEEL, THICKNESS: 0.25±0.03 mm.

2. FINISH

2-1 CONTACT: Ni 1.2um(50u") UNDERPLATED ALL OVER,

--ZONE A: 0.76um Au.

--ZONE B: SnPb 2.5um(100u") FOR 54040-001; PURE Sn 2.5 um FOR

54040-001-LF; EXCEPT CUT-OFF EDGES.
--ZONE B: MATTE PURE TIN 2.5~5um(100~200u").

(FOR LEAD FREE PLATING)

EXCEPT CUT-OFF EDGES.

2-2 SHIELD: Ni 1.2um(50u")

3. PACKAGE

3-1 PACKAGING SPECIFICATION: GES-14-532, PRODUCT TO BE

TAPED ON REEL PACKED.

4. WIDTH OF CONTACT

| CONTACT POSITION | WIDTH | | | | | |
|------------------|--------|--|--|--|--|--|
| 3,4,17 | 0.6 mm | | | | | |
| OTHERS | 0.4 mm | | | | | |

5. RECOMMENDED PCB LAYOUT

5-1 SEE SHEET 2.

5-2 THE SHIELD FOUR PEGS AND BOTTOM SURFACE SHOULD BE SOLDERED.

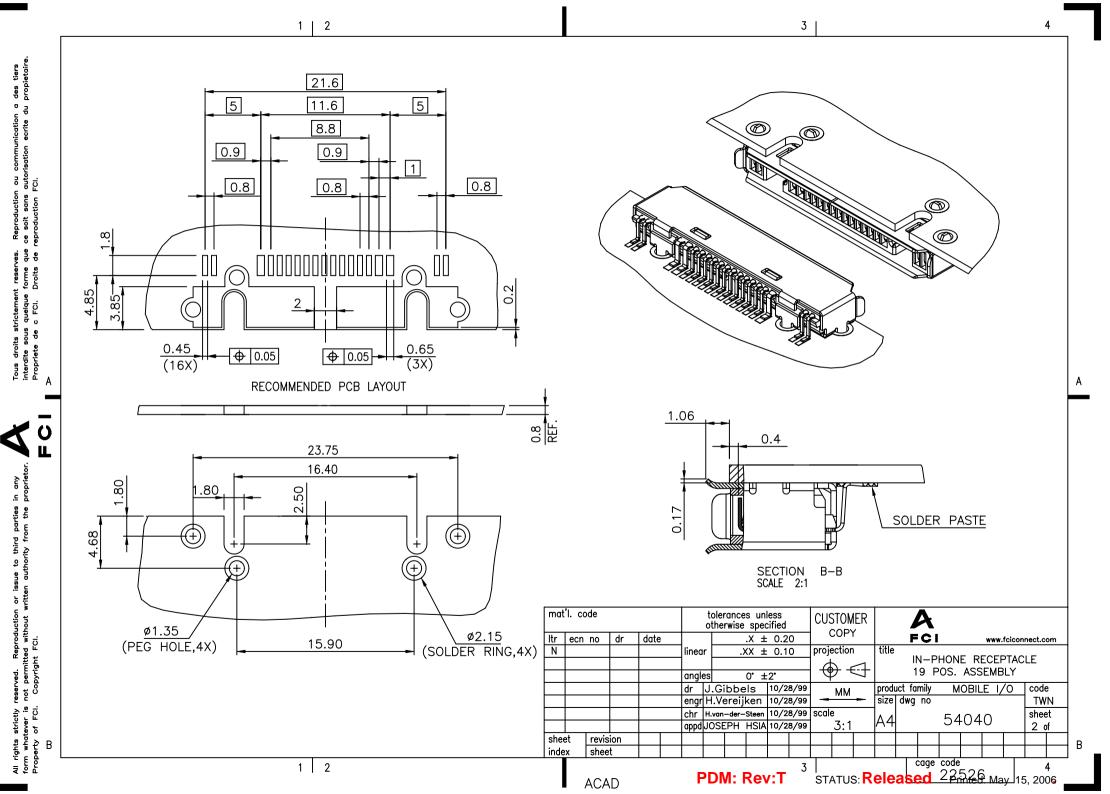
6. SUFFIX "-LF" OF 54040-001-LF MEANS FOR LEAD FREE PRODUCT. 54040-001-LF CAN MEETS EUROPEAN UNION D OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008. LEAD FREE LABEL ON REEL & CARTON OF 54040-001-LF PER GS-14-920

 THE HOUSING WILL WITHSTAND EXPOSURE TO 260° PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN

| mat | t'l. cod | de | | | | tolerances unless otherwise specified | | | | | | | CUSTOMER COPY | | | | A | | | | | | | |
|------|---------------|----------------------|-----|------|------|--|--------------------------|------------|------|----------|----------|------------|------------------|-------|---------------------|---------------------|-------|--|------|--------|--------|--------|-----|--|
| ltr | ecn | no | dr | date | ; | | | | .X ± | 0.2 | 0 | projection | | | | FCI www.fciconnect. | | | | | | nect.c | om | |
| L | T03-0 | 0138 | M W | 04/2 | 4/03 | linea | r 🗀 | | XX ± | 0.1 | 0 | | | | title | | | | | | | | | |
| М | T04-0 | 0065 | M W | 02/1 | 8/04 | | | | | | | 1 4 | 7 - | 1 | | IN-PHONE RECEPTAC | | | | | | LE | | |
| N | T04-0 | 0213 | M W | 05/2 | 7/04 | angl | es | 0° ±2° | | | | | | | | 19 POS. ASSEMBLY | | | | | | | | |
| Р | DG04- | G04-0056 PM 08/09/04 | | 9/04 | dr | J.G | J.Gibbels | | 10/2 | 8/99 | ММ | | | produ | oduct family MOBILE | | | | E 1/ | O code | | ; | | |
| R | DG04- | 0096 PM 12/13/04 | | | 3/04 | engr | r H.Vereijken 10/28/99 | | | | 8/99 | - | | - | size dwg no T | | | | | | | TW | TWN | |
| S | DG04-0105 P M | | | 12/2 | 4/04 | chr | hr H.van-der-Steen | | | 10/28/99 | | scale | | المما | 54040 | | | | | | sheet | | | |
| T | DG05-0574 P M | | | 01/0 | 3/06 | appd | JOSE | OSEPH HSIA | | | 10/28/99 | | 2:1 | | A4 | | 34040 | | | | 1 of 8 | | | |
| she | heet re | | ion | T | N | R | Ν | Р | Р | R | Α | | | | | | | | | | | | | |
| inde | index sheet | | t | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | | | | | | | | | | | | | |

PDM: Rev:T

STATUS: Release 5 2 ted: May 15, 2006



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sheet

3 of

1 | 2 3 PRODUCT NUMBER REMARK 5404D-002 BDTTOM MOUNT BDTTOM MOUNT 5404D-002-LF 24.00 2.D5+0.15 2.05 10.15 (ZONE (NOTE 2-2/2-5) 4X 24.80 (NOTE 2-2/2-5) NOTES: 0.40 4 0.10 1. MATERIAL 1-1 1 HOUSING: HIGH TEMP, PLASTIC, LCP OR EQUIVALENT. [18X] 4.2世紀3 0.6D A 2.86 0.25±0.D3 UL94V-O, COLOR BLACK. (3X) (2X) -1-2 @ CONTACT: COPPER ALLDY, THICKNESS: 0.15±0.02 mm. RAW MAT'L NUST SUPPLIED BY NIPPON MINING. DETAIL A 1-3 (3) SHIELD: STAINLESS STEEL, THICKNESS: 0,25±0,03 mm. 2. FINISH 2-1 CONTACT: Ni 1.2um(50u") UNDERPLATED ALL OVER, --ZONE A: D.76um Au. -- ZONE B: SnPb 2.5um(1DQu") FOR 54040-0D2; PURE Sn 2.5 um FOR Contact 1 -(2) 1.80 Contact 19 54D40-D02-LF EXCEPT CUT-OFF EDGES. 2-2 5HELD: Ni 1.2um(50u") 16.7D 3. PACKAGE 3-1 PACKAGING SPECIFICATION: GES-14-532, PRODUCT TO BE TAPED DN REEL PACKED. 4. WIDTH OF CONTACT (3)-O.B (ZONE B) O.GS 158 (FROM CONTACT POSITION | WIDTH 3,4,17 0.6 mm OTHERS 0.4 mm □ 0.1 5. RECOMMENDED PCB LAYOUT 5-1 SEE SHEET 2. D.3±0.03 ⊕ D.15 O" +10" 0.5±0.03 5-2 THE SHIELD FOUR PEGS AND BOTTOM SURFACE SHOULD **⊕** 0.15 (16X) BE SOLDERED. 0.8 D.8 0.8 6. SUFFIX "-LF" OF 54040-002-LF NEANS FOR LEAD FREE PRODUCT. 54040-002-LF 0,9 CAN MEETS EUROPEAN UNION DIDTHER COUNTRY REQULATIONS AS DESCRIBED IN 0.9 GS-22-GD8. LEAD FREE LABEL ON REEL & CARTON OF 54D40-D02-LF PER 11XD.8=8.8 7. THE HOUSING WILL WITHSTAND EXPOSURE TO 260° PEAK TEMPERATURE FOR 1D 11.6 5 DETAIL A SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN SCALE 4:1 21.6 mat'l. cade tolerances unless CUSTOMER otherwise specified COPY FCI .X ± 0.20 ecn no www.fciconnect.com .XX ± 0.10 inear IN-PHONE RECEPTACLE (NOTE 5-2,4X)/ 19 POS. ASSEMBLY 0° ±2° 15.9D 23.75 MOBILE I/O J.Gibbels 10/28/99 MM

sheet

1 2

revision sheet

PDM: Rev:T

engr H.Vereijken 10/28/99 chr H.van-der-Steen 10/28/99

oppd JOSEPH HSIA 1D/28/99

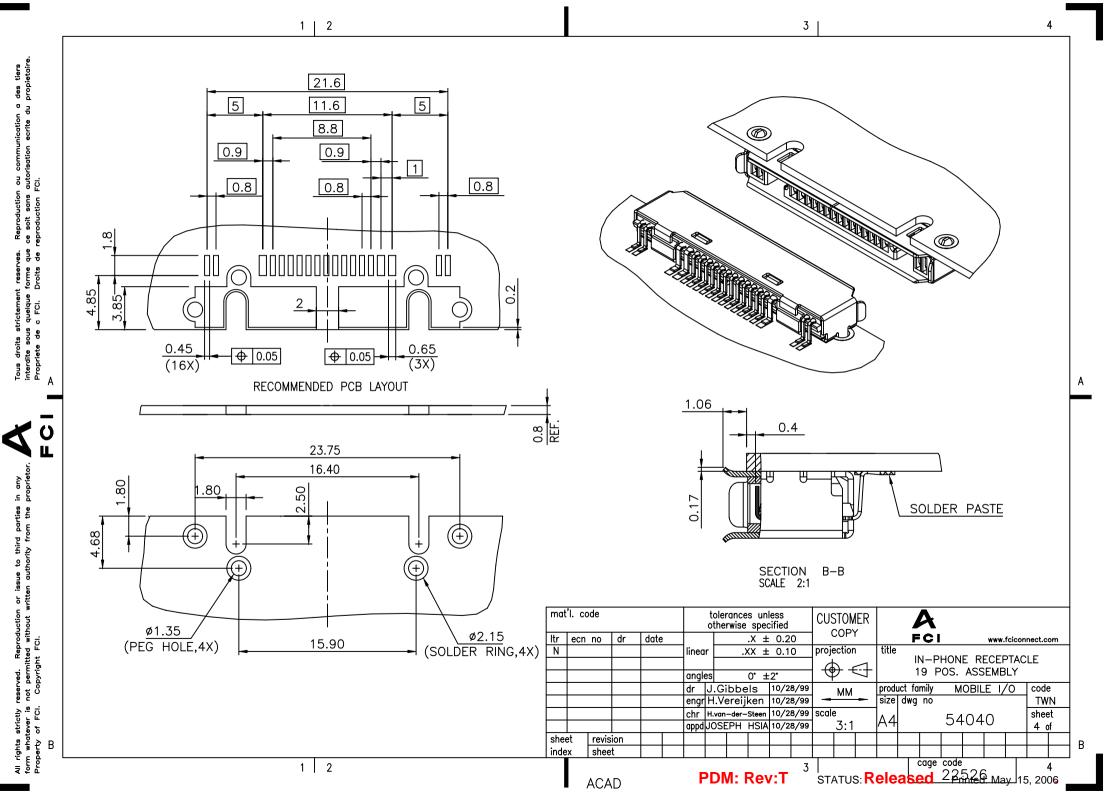
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54040

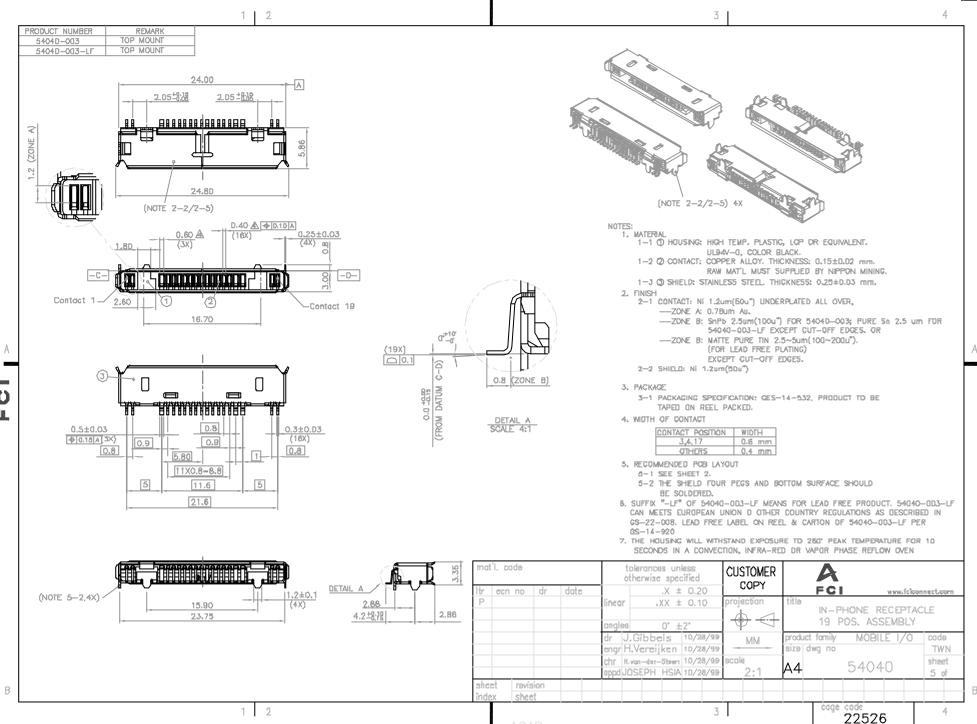
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size dwg no

Α4

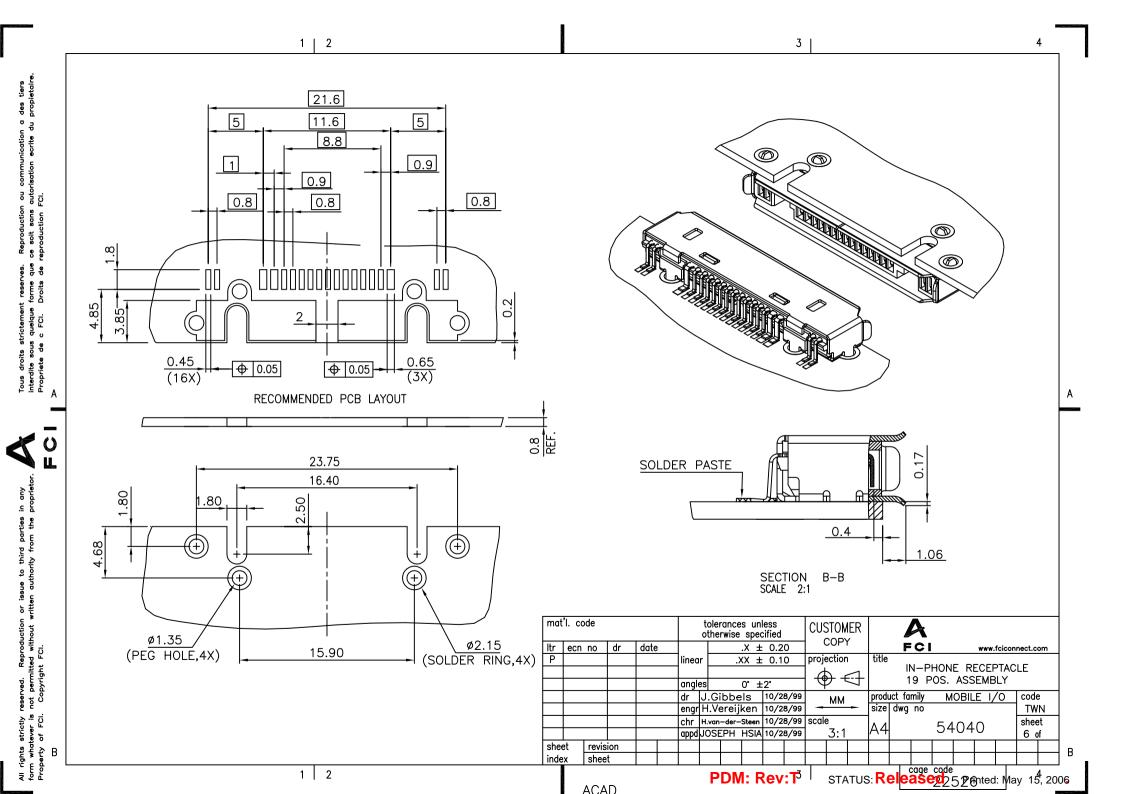






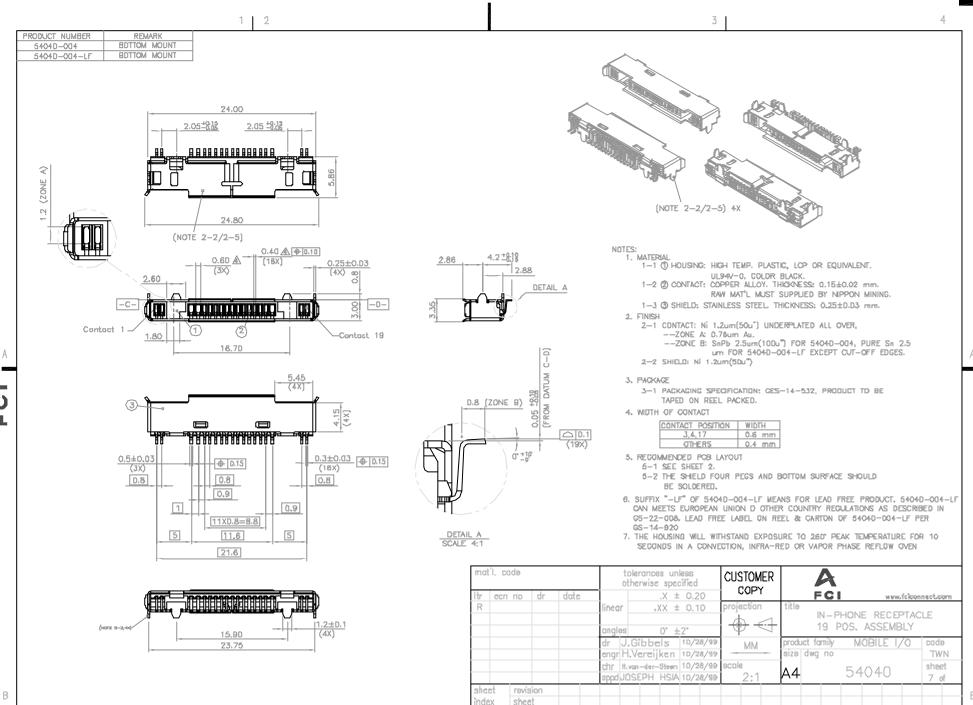
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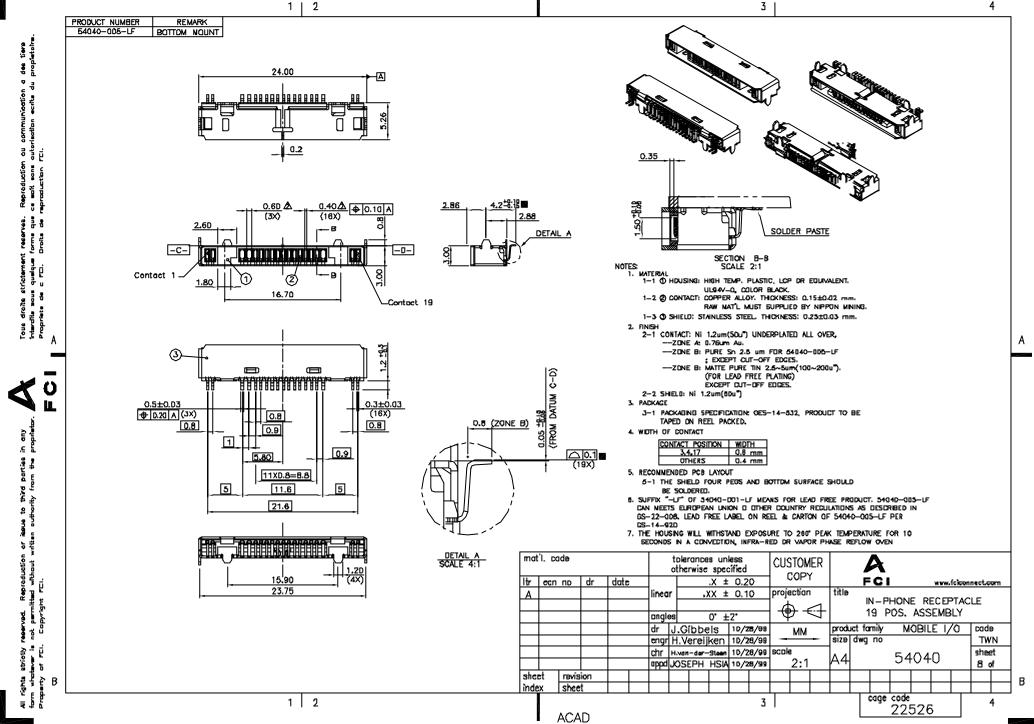
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PDM: Rev:T

STATUS: Released Printed: May 15, 2006

22526



PDM: Rev:T STATUS: Release

STATUS: Released Printed: May 15, 2006